

描述 / Descriptions

表面贴装肖特基二极管，反向电压：40V，正向电流：3.0A，薄型 SMBF 封装。
Surface Mount Schottky Barrier Rectifier, Reverse Voltage:40V,Forward Current:3.0A,SMBF thin package.

特征 / Features

低功耗，高效率，浪涌电流大，适用于低压，高频和极性保护，适用于表面贴装。无卤产品。
Low power loss, high efficiency, High forward surge current capability, For use in low voltage, high frequency inverters, and polarity protection applications,For surface mounted applications.Halogen free product.

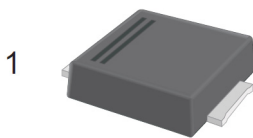
用途 / Applications

一般用途。
General purpose.

内部等效电路 / Equivalent Circuit

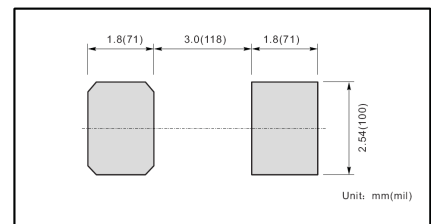


引脚排列 / Pinning



| PIN | DESCRIPTION |
|-----|-------------|
| 1 | Cathode |
| 2 | Anode |

The recommended mounting pad size



印章代码 / Marking

见印章说明。See Marking Instructions.

极限参数 / Absolute Maximum Ratings(Ta=25°C)

| 参数 Parameter | 参数符号 Symbol | 数值 Rating | 单位 Unit |
|---|-----------------|--------------|------------|
| Maximum Repetitive Peak Reverse Voltage | V_{RRM} | 40 | V |
| Maximum RMS voltage | V_{RMS} | 28 | V |
| Maximum DC Blocking Voltage | V_{DC} | 40 | V |
| Maximum Average Forward Rectified Current at $T_c=100^\circ\text{C}$ | $I_F (AV)$ | 3.0 | A |
| Peak Forward Surge Current,8.3ms Single Half Sine-wave Superimposed on Rated Load | I_{FSM} | 80 | A |
| Typical Junction Capacitance ¹⁾ | C_j | 350 | pF |
| Typical Thermal Resistance ²⁾ | $R_{\theta JA}$ | 47 | °C/W |
| Operating Junction Temperature Range | T_j | -55~+150 | °C |
| Storage Temperature Range | T_{stg} | -55~+150 | °C |

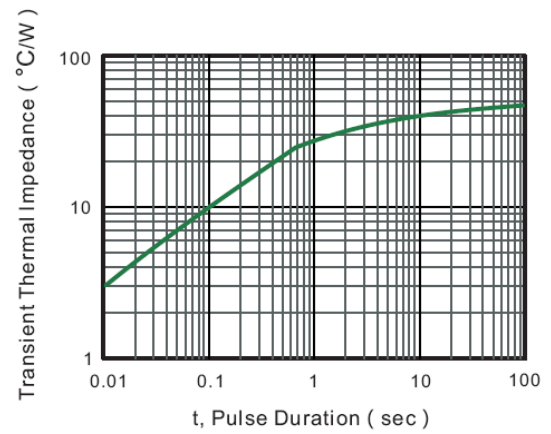
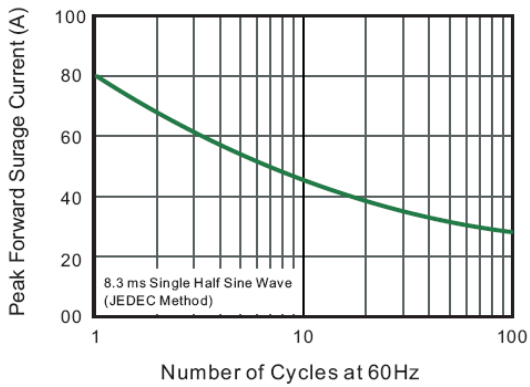
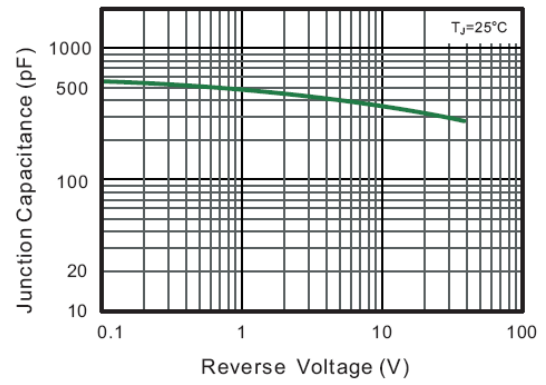
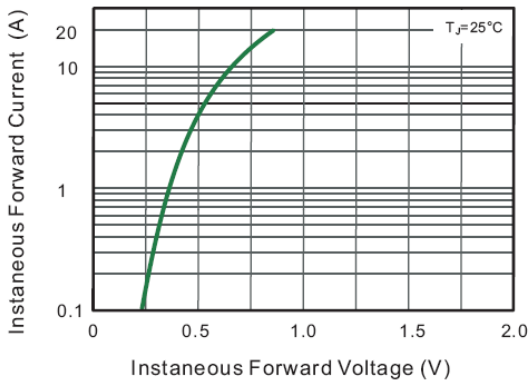
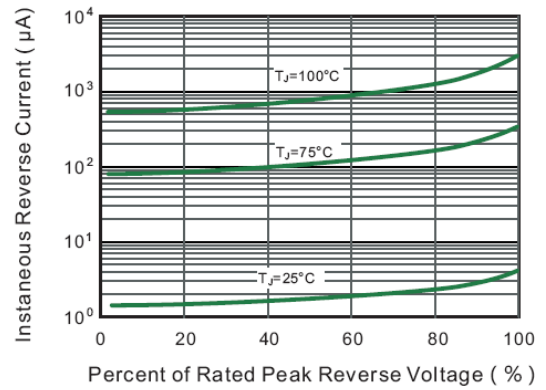
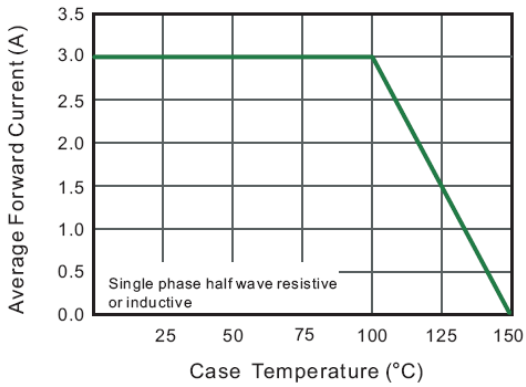
Note:

- 1) Measured at 1MHz and applied reverse voltage of 4 V D.C.
- 2) P.C.B. mounted with 2.0 X 2.0" (5 X 5 cm) copper pad areas.

电性能参数 / Electrical Characteristics(Ta=25°C)

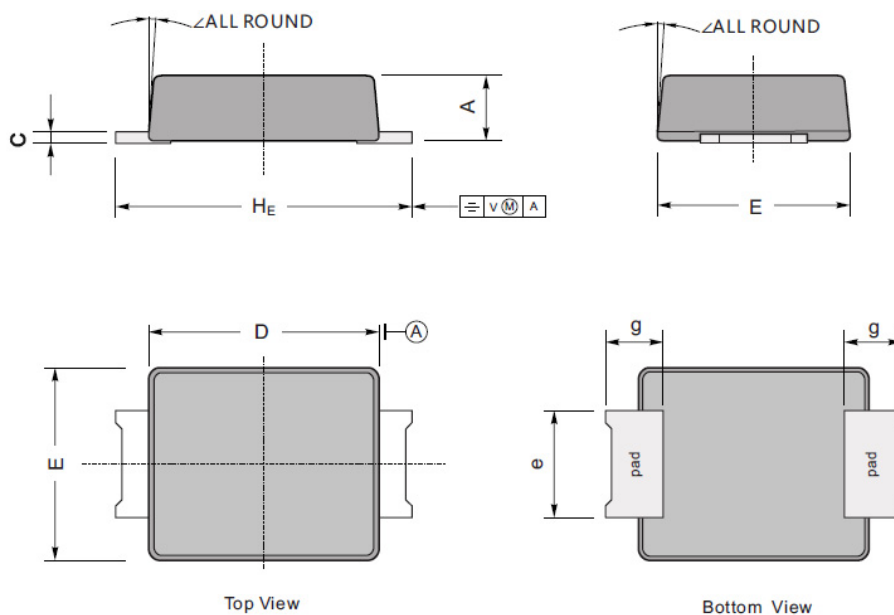
| 参数 Parameter | 参数符号 Symbol | 测试条件 Test condition | 数值 Rating | 单位 Unit |
|--|----------------|-------------------------|--------------|------------|
| Max Instantaneous Forward Voltage | V_F | $I_F=3.0A$ | 0.45 | V |
| Maximum DC Reverse Current at Rated DC Reverse Voltage | I_R | $T_a=25^\circ\text{C}$ | 0.3 | mA |
| | | $T_a=100^\circ\text{C}$ | 5 | |

电参数曲线图 / Electrical Characteristic Curve



外形尺寸图 / Package Dimensions

SMBF



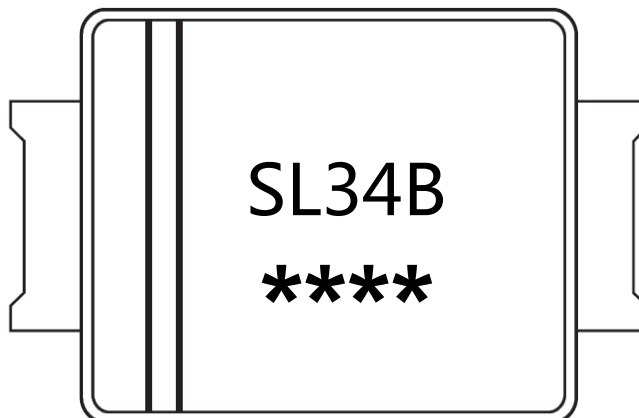
| UNIT | | A | C | D | E | H_E | e | g | \angle |
|------|-----|-----|------|-----|-----|-------|-----|-----|----------|
| mm | max | 1.3 | 0.26 | 4.4 | 3.7 | 5.5 | 2.2 | 1.0 | 9° |
| | min | 1.1 | 0.18 | 4.2 | 3.5 | 5.1 | 1.9 | | |
| mil | max | 51 | 10 | 173 | 146 | 216 | 86 | 40 | |
| | min | 43 | 7 | 165 | 138 | 200 | 75 | | |

印章说明 / Marking Instructions

Marking

| Type number | Marking code |
|-------------|--------------|
| SSL34BF | SL34B |

印章说明 / Marking Instructions



说明：

SL34B： 为型号代码

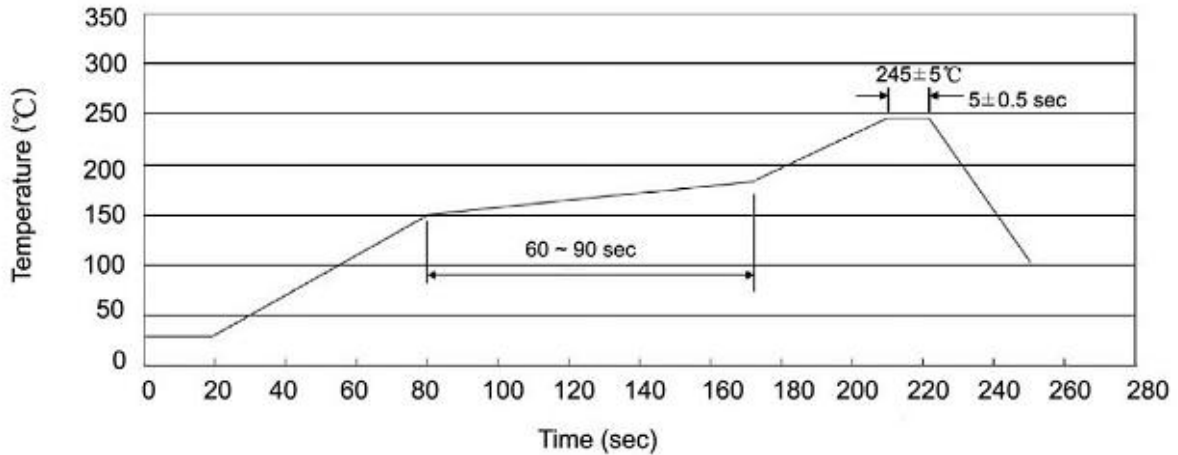
****： 为生产批号追溯码，第1个*为年月代码，后面3个*为当月小批号代码

Note:

SL34B： Product Type Code

****： Lot No. Code，The 1st * means:YM Code，The last 3 * means:little Lot No Code

回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)



说明：

- 1、预热温度 150 ~ 180°C，时间 60 ~ 90sec;
- 2、峰值温度 245±5°C，时间持续为 5±0.5sec;
- 3、焊接制程冷却速度为 2 ~ 10°C/sec.

Note:

- 1.Preheating:150~180°C, Time:60~90sec.
- 2.Peak Temp.:245±5°C, Duration:5±0.5sec.
3. Cooling Speed: 2~10°C/sec.

耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions

温度：260±5°C

时间：10±1 sec.

Temp.:260±5°C

Time:10±1 sec

包装规格 / Packaging SPEC.

卷盘包装 / REEL

| Package Type 封装形式 | Units 包装数量 | | | | | Dimension 包装尺寸 (unit: mm ³) | | |
|----------------------|--------------------|-------------------------|------------------------|------------------------------|------------------------|---|-------------|-------------|
| | Units/Reel 只/卷盘 | Reels/Inner Box 卷盘/盒 | Units/Inner Box 只/盒 | Inner Boxes/Outer Box 盒/箱 | Units/Outer Box 只/箱 | Reel | Inner Box 盒 | Outer Box 箱 |
| SMBF | 5000 | 2 | 10000 | 5 | 50000 | 13" ×15 | 336X332X40 | 380X335X366 |

使用说明 / Notices